



NSAI
Standards

Irish Standard
I.S. EN 62047-10:2011

Semiconductor devices - Micro-
electromechanical devices -- Part 10:
Micro-pillar compression test for MEMS
materials (IEC 62047-10:2011 (EQV))

I.S. EN 62047-10:2011

Incorporating amendments/corrigenda issued since publication:

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EUROPEAN STANDARD

EN 62047-10

NORME EUROPÉENNE

EUROPÄISCHE NORM

September 2011

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English version

**Semiconductor devices -
Micro-electromechanical devices -
Part 10: Micro-pillar compression test for MEMS materials
(IEC 62047-10:2011)**

Dispositifs à semiconducteur -
Dispositifs microélectromécaniques -
Partie 10: Essai de compression utilisant
la technique des micro-piliers pour les
matériaux des MEMS
(CEI 62047-10:2011)

Halbleiterbauelemente -
Bauelemente der Mikrosystemtechnik -
Teil 10: Druckprüfverfahren an
zylinderförmigen Mikroproben für
Werkstoffe der Mikrosystemtechnik
(IEC 62047-10:2011)

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CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

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Foreword

The text of document 47F/85/FDIS, future edition 1 of IEC 62047-10, prepared by SC 47F, Micro-electromechanical systems, of IEC TC 47, Semiconductor devices, was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 62047-10:2011.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2012-05-30
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2014-08-30

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Endorsement notice

The text of the International Standard IEC 62047-10:2011 was approved by CENELEC as a European Standard without any modification.

Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 62047-8	-	Semiconductor devices - Micro-electromechanical devices - Part 8: Strip bending test method for tensile property measurement of thin films	EN 62047-8	-

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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MICRO-ELECTROMECHANICAL DEVICES –**
Part 10: Micro-pillar compression test for MEMS materials

FOREWORD

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International Standard IEC 62047-10 has been prepared by subcommittee 47F: Micro-electromechanical systems, of IEC technical committee 47: Semiconductor devices.

The text of this standard is based on the following documents:

FDIS	Report on voting
47F/85/FDIS	47F/94/RVD

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts of IEC 62047, under the general title *Semiconductor devices – Micro-electromechanical devices*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
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